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(12) **United States Design Patent**
Sakai et al.

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(54) **CHIP CONNECTOR**

(71) Applicant: **Sony Corporation**, Tokyo (JP)

(72) Inventors: **Yoshitsugu Sakai**, Kanagawa (JP); **Masaaki Abe**, Kanagawa (JP); **Ichiro Fujii**, Chiba (JP)

(73) Assignee: **SONY CORPORATION**, Tokyo (JP)

(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 145, 184
CPC . F28D 15/0275; F28D 21/0003; F02M 26/32; F28F 1/025; F28F 3/022; F28F 21/00; H01L 23/3677; H01L 23/4334
See application file for complete search history.

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Primary Examiner — Jennifer Rivard
Assistant Examiner — April Rivas
(74) *Attorney, Agent, or Firm* — Michael Best and Friedrich LLP

(57) **CLAIM**

The ornamental design for a chip connector, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a chip connector showing our new design;
FIG. **2** is a front elevational view thereof; and,
FIG. **3** is an enlarged partial front elevational view cut along the line **3**-**3** of FIG. **2**.
The broken lines illustrating chip connector portions are unclaimed portions thereof and form no part of the claimed design. The dot-dash broken lines define the boundaries of, but are not included in, the claimed design.

1 Claim, 3 Drawing Sheets

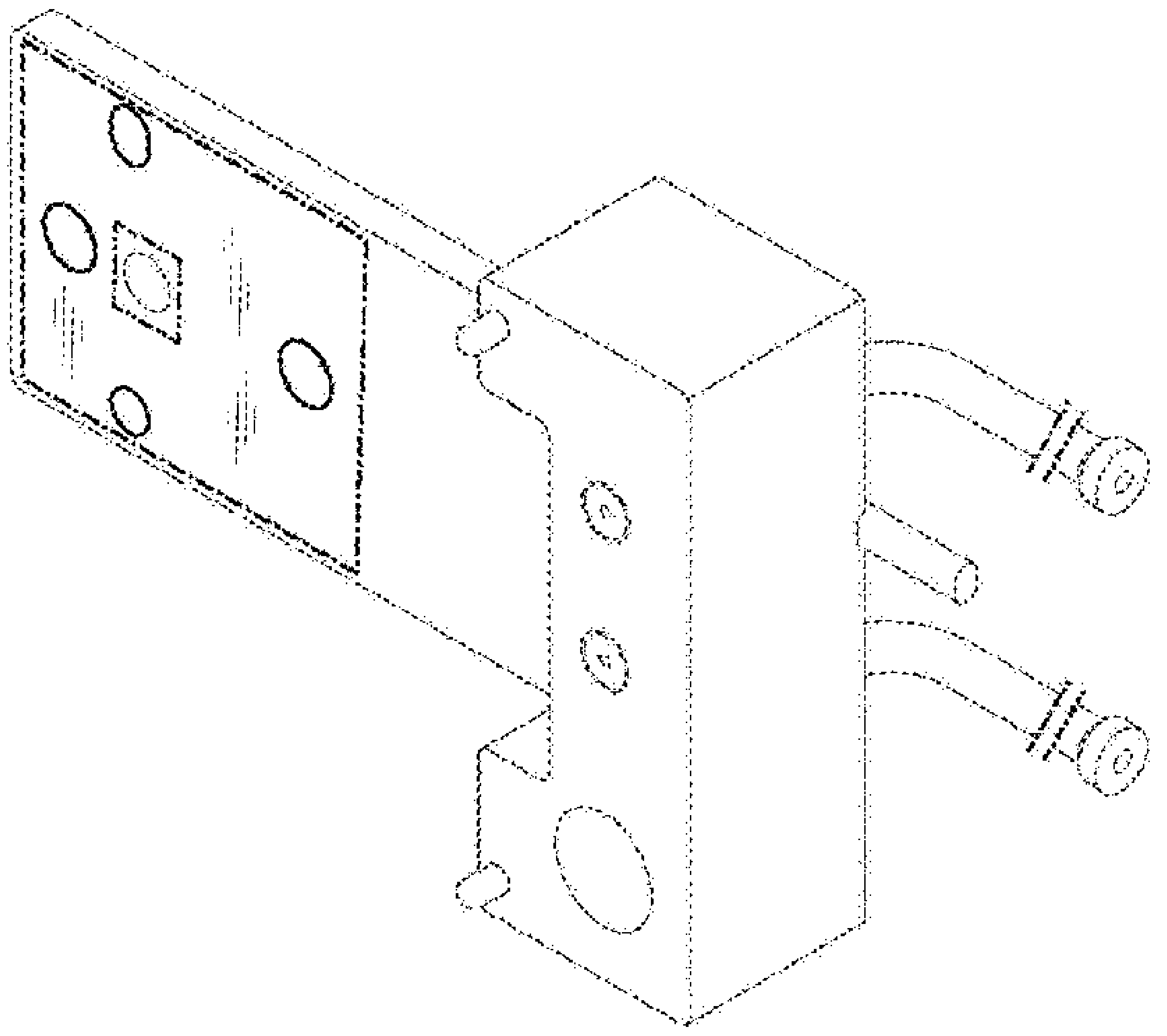

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FIG.1

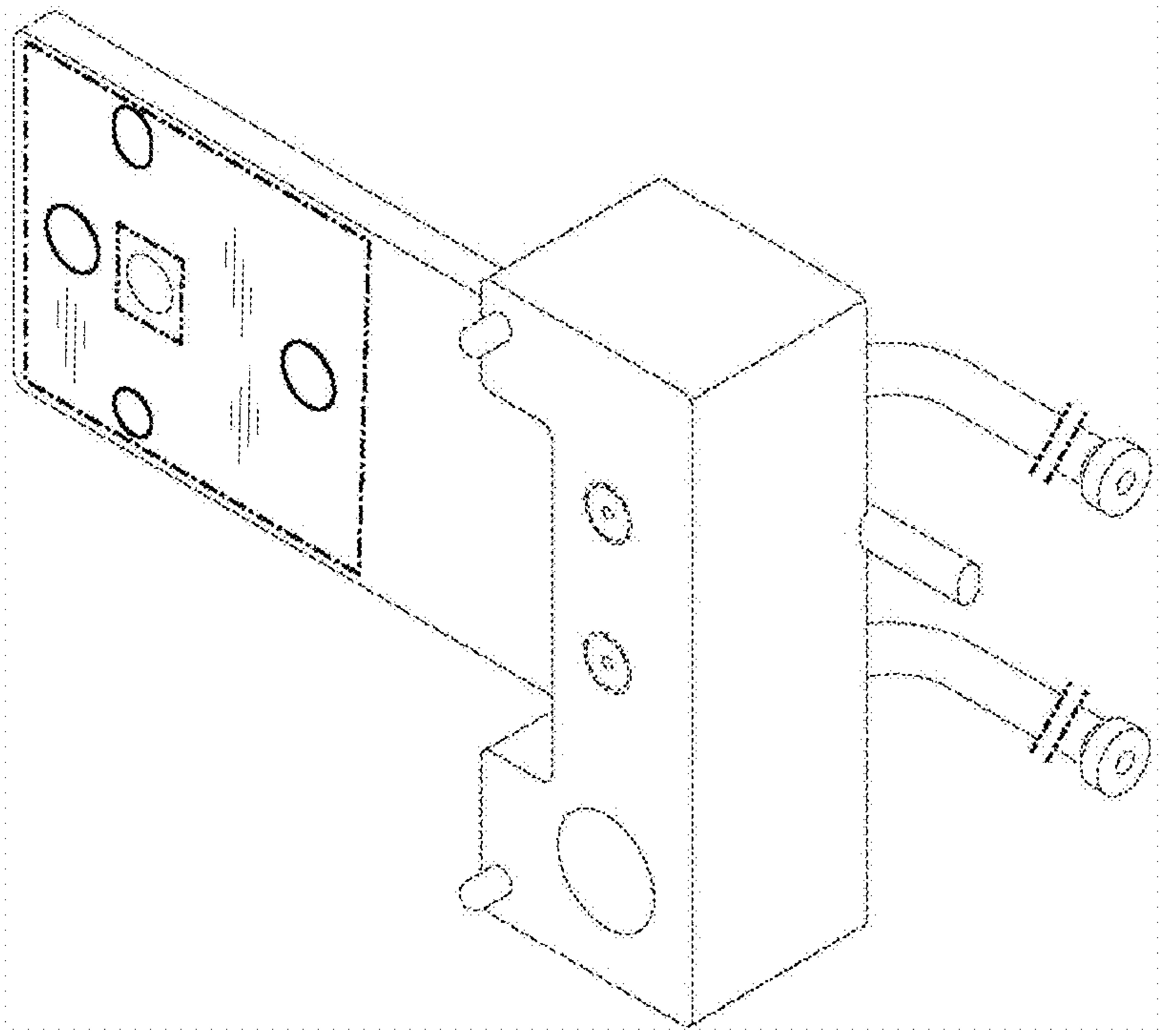

FIG.2

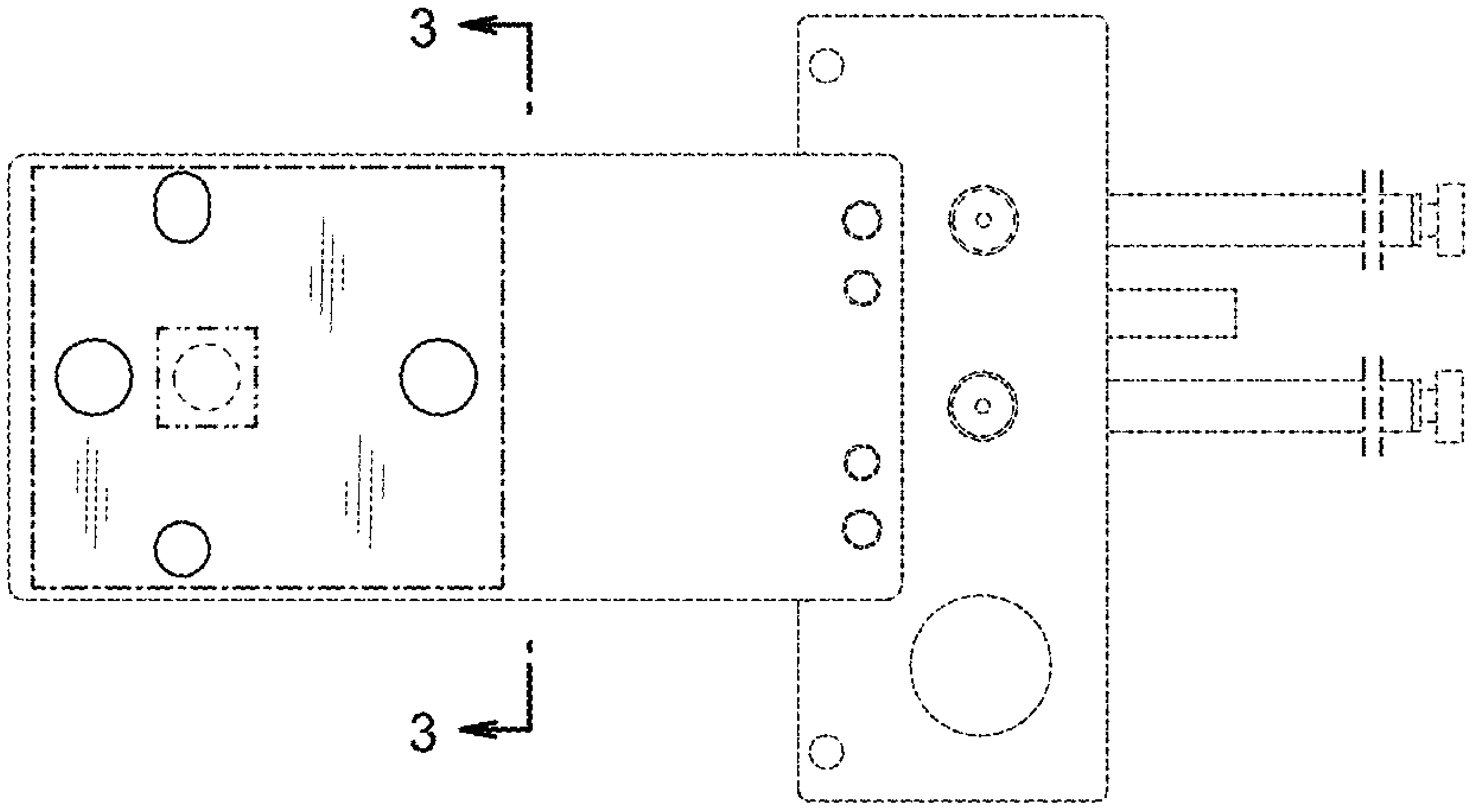

FIG.3